



## **CP4000**

The Logitech CP4000 is a corrosion resistant chemical polishing machine, integrated with a fume extraction enclosure. Designed for aggressive hazardous chemical polishing operations such as; Bromine Methanol or acid etches for prime face polishing of semiconductor wafers or electronic and optoelectronic crystals - the CP4000 has been designed exactly for this application and utilises a chemical etch polishing process to produce high quality results with minimal subsurface damage.

Robustly fabricated from polypropylene and other resistant materials makes this system suitable for use with most chemical polishing agents.

Typical applications for the CP4000 include final chemical etch polishing before device fabrication or epitaxial growth on a number of materials. This system is ideal for all applications requiring an electronic grade polish of the highest standard with minimal stressing of the crystalline structure.









## **KEY FEATURES & FUNCTIONALITY**

- → Benchtop, corrosion resistant chemical polishing machine with integrated fume extraction enclosure, designed for aggressive hazardous chemical polishing operations.
- → Standard work desk configuration accommodates the processing of up to nine samples mounted on to 83mm/3" support discs. These can be adapted on request to suit customers individual requirements.
- → Robustly constructed of polypropylene and other corrosion resistant materials making it suitable for use with most chemical polishing agents.
- → Two fluid feed bottles are located on the left side of the work deck that holds the etchant and diluent, allowing the peristaltic pump system to independently control the etchant and diluent fluid, from the Graphical User Interface (GUI), on to the polishing surface.
- → The CP4000 waste sump can hold up to 25 litres/5.5 gallons of used polishing fluid which is monitored by the capacity sensor allowing for longer process, uninterrupted by stopping the process to empty the waste.
- → The CP4000 is fitted with a lift-off glass plate to which a self-adhesive polishing cloth is fixed. Plates can be supplied in the range of 250mm-450mm/10″-18″. With minor adaption to the work deck area, wafers up to 200mm/8″ can be polished.
- → Process conditions can be controlled via the Graphical User Interface (GUI) on the CP4000 including plate speeds and polishing slurry flow rate.
- → Recipe mode allows users to build, save and re-call multi-stage recipes allowing for easy process repeatability even across different operators

→ Typical applications include fine etch polishing of semiconductor wafers & electro-optic crystals.

- 1: Logitech CP4000 Chemical Polishing System
- 2: Control process parameters via the GUI
- 3: Fluid feed system via peristaltic pumps
- 4: Standard workdeck configuration for processing up to 9 samples simultaneously

## **TECHNICAL SPECIFICATIONS**

Maximum Sample Size	9 of 83mm/3" diameter	
Height	1260mm	
Width	1370mm	
Depth	700mm	
Power Supply	230v 50/60Hz	
Plate Diameter	254-457mm/10"-18"	
Plate Speed	0-70rpm	
Timer	0-60 minutes	
Universal Drive Mechanism	0.18kW (0.25) DC Electric Motor	

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